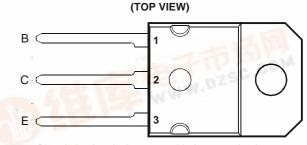
#### 查询BD545供应商

# <u>捷多邦,专业PCB打样工厂,24小时加急出货</u> BD545, BD545A, BD545B, BD545C NPN SILICON POWER TRANSISTORS

Copyright © 1997, Power Innovations Limited, UK

JUNE 1973 - REVISED MARCH 1997

- Designed for Complementary Use with the BD546 Series
- 85 W at 25°C Case Temperature
- 15 A Continuous Collector Current
- Customer-Specified Selections Available



SOT-93 PACKAGE

Pin 2 is in electrical contact with the mounting base.

### absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	BD545		40	9
Collector bose voltage (I _ 0)	BD545A	V	60	V
Collector-base voltage ( $I_E = 0$ )	BD545B	V <sub>CBO</sub>	80	v
	BD545C	AC WWW	100	
	BD545		40	
Collector-emitter voltage (I <sub>B</sub> = 0) (see Note 1)	BD545A		60	V
	BD545B	V <sub>CEO</sub>	80	v
	BD545C		100	
Emitter-base voltage	V <sub>EBO</sub>	5	V	
Continuous collector current			15	A
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)			85	W
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3)			3.5	W
Operating free air temperature range			-65 to +150	°C
Operating junction temperature range			-65 to +150	°C
Storage temperature range			-65 to +150	°C
Lead temperature 3.2 mm from case for 10 seconds			260	°C

NOTES: 1. These values apply when the base-emitter diode is open circuited.

2. Derate linearly to 150°C case temperature at the rate of 0.68 W/°C.

3. Derate linearly to 150°C free air temperature at the rate of 28 mW/°C.



ofoll

orily include testing

with the terms of Power Innovations standard warranty. Production processing does not



JUNE 1973 - REVISED MARCH 1997

## electrical characteristics at 25°C case temperature

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
V <sub>(BR)CEO</sub>	Collector-emitter breakdown voltage	(see Note 4)		BD545				
			I <sub>В</sub> = 0	BD545A	60			V
				BD545B	D545B 80			
				BD545C	100			L
	Collector-emitter cut-off current	V <sub>CE</sub> = 40 V	$V_{BE} = 0$	BD545			0.4	
1		$V_{CE} = 60 V$	$V_{BE} = 0$	BD545A			0.4	mA
ICES		V <sub>CE</sub> = 80 V	$V_{BE} = 0$	BD545B			0.4	
		V <sub>CE</sub> = 100 V	$V_{BE} = 0$	BD545C			0.4	
I <sub>CEO</sub>	Collector cut-off	V <sub>CE</sub> = 30 V	I <sub>B</sub> = 0	BD545/545A			0.7	mA
	current	V <sub>CE</sub> = 60 V	I <sub>B</sub> = 0	BD545B/545C			0.7	IIIA
I <sub>EBO</sub>	Emitter cut-off current	V <sub>EB</sub> = 5 V	$I_{\rm C} = 0$				1	mA
	Forward current	$V_{CE} = 4 V$	I <sub>C</sub> = 1 A		60			
h <sub>FE</sub>	transfer ratio	$V_{CE} = 4 V$	I <sub>C</sub> = 5 A	(see Notes 4 and 5)	25			
		$V_{CE} = 4 V$	I <sub>C</sub> = 10 A		10			
V	Collector-emitter	I <sub>B</sub> = 625 mA	I <sub>C</sub> = 5 A	(see Notes 4 and 5)			0.8	V
V <sub>CE(sat)</sub>	saturation voltage	I <sub>B</sub> = 2 A	I <sub>C</sub> = 10 A				1	v
$V_{BE}$	Base-emitter voltage	V <sub>CE</sub> = 4 V	I <sub>C</sub> = 10 A	(see Notes 4 and 5)			1.8	V
h <sub>fe</sub>	Small signal forward current transfer ratio	V <sub>CE</sub> = 10 V	I <sub>C</sub> = 0.5 A	f = 1 kHz	20			
h <sub>fe</sub>	Small signal forward current transfer ratio	V <sub>CE</sub> = 10 V	I <sub>C</sub> = 0.5 A	f = 1 MHz	3			

NOTES: 4. These parameters must be measured using pulse techniques,  $t_p$  = 300 µs, duty cycle  $\leq$  2%.

5. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

#### thermal characteristics

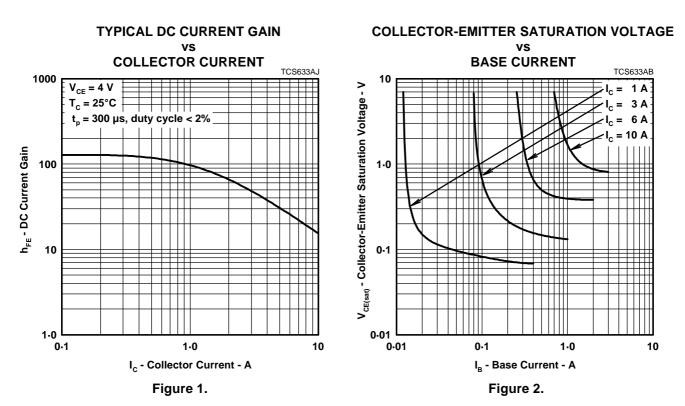
PARAMETER			TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.47	°C/W
$R_{\thetaJA}$	Junction to free air thermal resistance			35.7	°C/W

### resistive-load-switching characteristics at 25°C case temperature

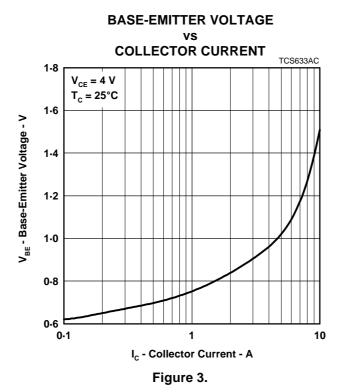
PARAMETER	TEST CONDITIONS <sup>†</sup>			MIN	ТҮР	MAX	UNIT
t <sub>on</sub> Turn-on time	I <sub>C</sub> = 6 A	$I_{B(on)} = 0.6 A$	I <sub>B(off)</sub> = -0.6 A		0.6		μs
t <sub>off</sub> Turn-off time	$V_{BE(off)} = -4 V$	$R_L = 5 \Omega$	$t_p$ = 20 µs, dc $\leq$ 2%		1		μs

<sup>†</sup> Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

JUNE 1973 - REVISED MARCH 1997



# **TYPICAL CHARACTERISTICS**





PRODUCT INFORMATION

JUNE 1973 - REVISED MARCH 1997



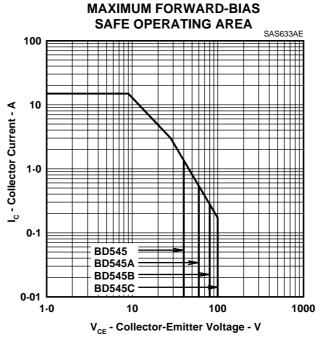


Figure 4.

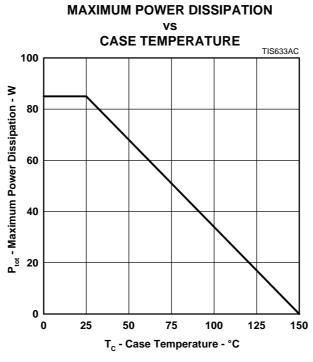




Figure 5.

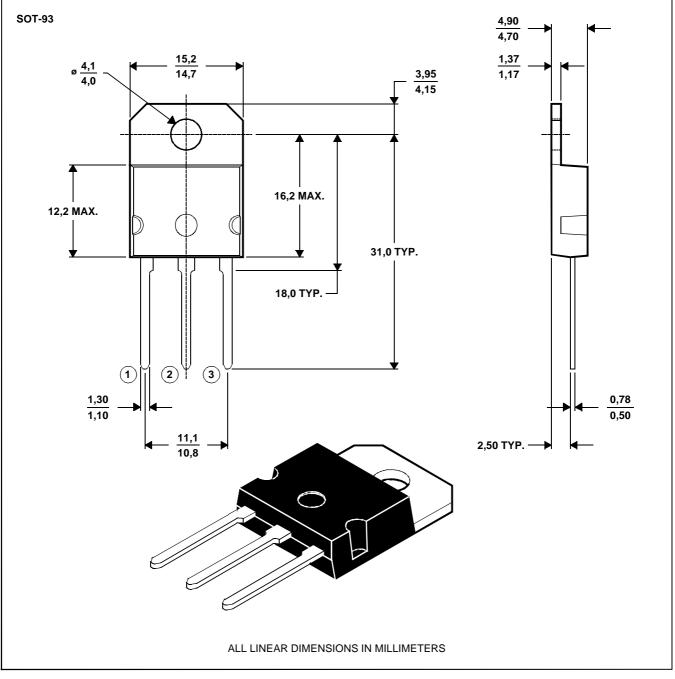
JUNE 1973 - REVISED MARCH 1997

# **MECHANICAL DATA**

### **SOT-93**

## 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

MDXXAW



### PRODUCT INFORMATION

JUNE 1973 - REVISED MARCH 1997

### **IMPORTANT NOTICE**

Power Innovations Limited (PI) reserves the right to make changes to its products or to discontinue any semiconductor product or service without notice, and advises its customers to verify, before placing orders, that the information being relied on is current.

PI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with PI's standard warranty. Testing and other quality control techniques are utilized to the extent PI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except as mandated by government requirements.

PI accepts no liability for applications assistance, customer product design, software performance, or infringement of patents or services described herein. Nor is any license, either express or implied, granted under any patent right, copyright, design right, or other intellectual property right of PI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used.

PI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, INTENDED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT APPLICATIONS, DEVICES OR SYSTEMS.

Copyright © 1997, Power Innovations Limited